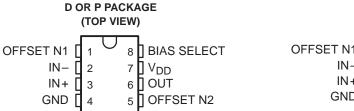
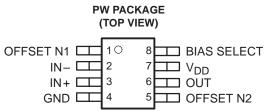
- Wide Range of Supply Voltages Over Specified Temperature Range:
   T<sub>A</sub> = -40°C to 85°C . . . 2 V to 8 V
  - Fully Characterized at 3 V and 5 V
- Single-Supply Operation
- Common-Mode Input-Voltage Range Extends Below the Negative Rail and up to V<sub>DD</sub> -1 V at 25°C
- Output Voltage Range Includes Negative Rail

- High Input Impedance . . . 10<sup>12</sup> Ω Typ
- Low Noise . . . 25 nV/√Hz Typically at f = 1 kHz (High-Bias Mode)
- ESD-Protection Circuitry
- Designed-In Latch-Up Immunity
- Bias-Select Feature Enables Maximum Supply Current Range From 17 μA to 1.5 mA at 25°C





#### description

The TLV2341 operational amplifier has been specifically developed for low-voltage, single-supply applications and is fully specified to operate over a voltage range of 2 V to 8 V. The device uses the Texas Instruments silicon-gate LinCMOS™ technology to facilitate low-power, low-voltage operation and excellent offset-voltage stability. LinCMOS™ technology also enables extremely high input impedance and low bias currents allowing direct interface to high-impedance sources.

The TLV2341 offers a bias-select feature, which allows the device to be programmed with a wide range of different supply currents and therefore different levels of ac performance. The supply current can be set at  $17 \mu A$ ,  $250 \mu A$ , or 1.5 m A, which results in slew-rate specifications between 0.02 and  $2.1 \text{ V/}\mu s$  (at 3 V).

The TLV2341 operational amplifiers are especially well suited to single-supply applications and are fully specified and characterized at 3-V and 5-V power supplies. This low-voltage single-supply operation combined with low power consumption makes this device a good choice for remote, inaccessible, or portable battery-powered applications. The common-mode input range includes the negative rail.

The device inputs and outputs are designed to withstand –100-mA currents without sustaining latch-up. The TLV2341 incorporates internal ESD-protection circuits that prevents functional failures at voltages up to 2000 V as tested under MIL-STD 883 C, Methods 3015.2; however, care should be exercised in handling these devices as exposure to ESD may result in the degradation of the device parametric performance.

#### **AVAILABLE OPTIONS**

ſ			Р	ACKAGED DE	VICES	CHIP
	TA	V <sub>IO</sub> max AT 25°C	SMALL OUTLINE (D)	PACKAGED DEVICES  PLASTIC DIP (P)  TIV0344ID TIV0344IDWIF		FORM (Y)
ľ	-40°C to 85°C	8 mV	TLV2341ID TLV2341IP TLV2341IPW		TLV2341IPWLE	TLV2341Y

The D package is available taped and reeled. Add R suffix to the device type (e.g., TLV2341IDR). The PW package is only available left-end taped and reeled (e.g., TLV2341IPWLE).

LinCMOS is a trademark of Texas Instruments Incorporated.



#### bias-select feature

The TLV2342 offers a bias-select feature that allows the user to select any one of three bias levels, depending on the level of performance desired. The tradeoffs between bias levels involve ac performance and power dissipation (see Table 1).

	TYPICAL PARAMETER VALUES		MODE					
	$T_A = 25^{\circ}C$ , $V_{DD} = 3 \text{ V}$	HIGH BIAS $R_L = 10 \text{ k}\Omega$	MEDIUM BIAS $R_L = 100 \text{ k}\Omega$	LOW BIAS $R_L = 1 M\Omega$	UNIT			
PD	Power dissipation	975	195	15	μW			
SR	Slew rate	2.1	0.38	0.02	V/μs			
٧n	Equivalent input noise voltage at f = 1 kHz	25	32	68	nV/√Hz			
B <sub>1</sub>	Unity-gain bandwidth	790	300	27	kHz			
φm	Phase margin	46°	39°	34°				
A <sub>VD</sub>	Large-signal differential voltage amplification	11	83	400	V/mV			

Table 1. Effect of Bias Selection on Performance

#### bias selection

Bias selection is achieved by connecting BIAS SELECT to one of three voltage levels (see Figure 1). For medium-bias applications, it is recommended that the bias-select pin be connected to the midpoint between the supply rails. This procedure is simple in split-supply applications since this point is ground. In single-supply applications, the medium-bias mode necessitates using a voltage divider as indicated in Figure 1. The use of large-value resistors in the voltage divider reduces the current drain of the divider from the supply line. However, large-value resistors used in conjunction with a large-value capacitor require significant time to charge up to the supply midpoint after the supply is switched on. A voltage other than the midpoint may be used if it is within the voltages specified in the following table.

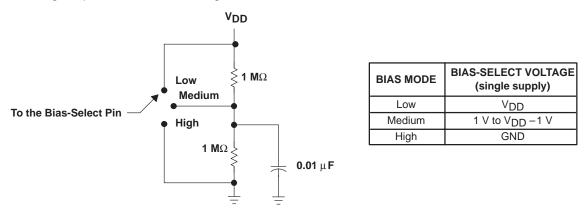


Figure 1. Bias Selection for Single-Supply Applications



#### high-bias mode

In the high-bias mode, the TLV2341 series feature low offset voltage drift, high input impedance, and low noise. Speed in this mode approaches that of BiFET devices but at only a fraction of the power dissipation.

#### medium-bias mode

The TLV2341 in the medium-bias mode features a low offset voltage drift, high input impedance, and low noise. Speed in this mode is similar to general-purpose bipolar devices but power dissipation is only a fraction of that consumed by bipolar devices.

#### low-bias mode

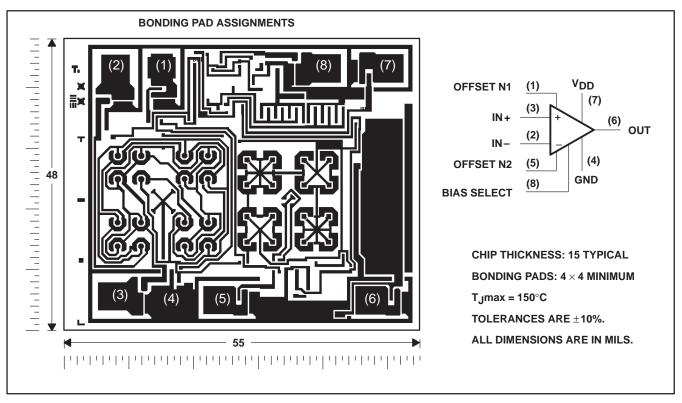
In the low-bias mode, the TLV2341 features low offset voltage drift, high input impedance, extremely low power consumption, and high differential voltage gain.

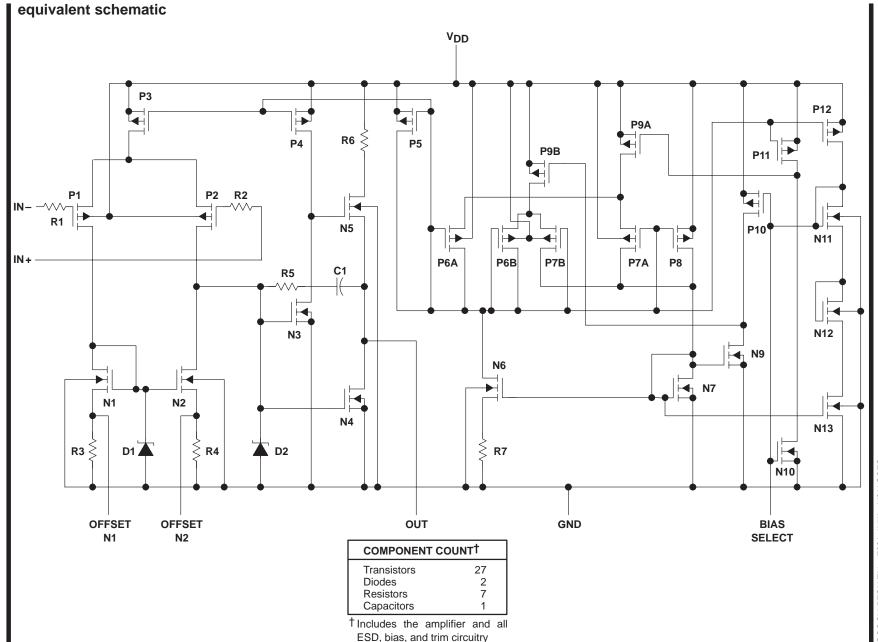
#### **ORDER OF CONTENTS**

TOPIC	BIAS MODE
Schematic	all
Absolute maximum ratings	all
Recommended operating conditions	all
Electrical characteristics Operating characteristics Typical characteristics	high (Figures 2 – 31)
Electrical characteristics Operating characteristics Typical characteristics	medium (Figures 32 – 61)
Electrical characteristics Operating characteristics Typical characteristics	low (Figures 62 – 91)
Parameter measurement information	all
Application information	all

#### **TLV2341Y chip information**

This chip, when properly assembled, displays characteristics similar to the TLV2341. Thermal compression or ultrasonic bonding may be used on the doped-aluminum bonding pads. Chips may be mounted with conductive epoxy or a gold-silicon preform.





#### TLV2341, TLV2341Y LinCMOS™ PROGRAMMABLE LOW-VOLTAGE OPERATIONAL AMPLIFIERS

SLOS110A - MAY 1992 - REVISED AUGUST 1994

#### absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

Supply voltage, V <sub>DD</sub> (see Note 1)	
Differential input voltage (see Note 2)	
Input voltage range, V <sub>I</sub> (any input)	0.3 V to V <sub>DD</sub>
Input current, I <sub>I</sub>	±5 mA
Output current, IO	±30 mA
Duration of short-circuit current at (or below) $T_A = 25^{\circ}C$ (see Note 3)	unlimited
Continuous total dissipation	See Dissipation Rating Table
Operating free-air temperature range, T <sub>A</sub>	–40°C to 85°C
Storage temperature range	
Lead temperature 1,6 mm (1/16 inch) from case for 10 seconds	260°C

<sup>†</sup> Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may effect device reliability.

- NOTES: 1. All voltage values, except differential voltages, are with respect to network ground.
  - 2. Differential voltages are at the noninverting input with respect to the inverting input.
  - 3. The output may be shorted to either supply. Temperature and/or supply voltages must be limited to ensure that the maximum dissipation rating is not exceeded (see application section).

#### **DISSIPATION RATING TABLE**

PACKAGE	$T_{\mbox{A}} \le 25^{\circ}\mbox{C}$ POWER RATING	DERATING FACTOR ABOVE T <sub>A</sub> = 25°C	T <sub>A</sub> = 85°C POWER RATING
D	725 mW	5.8 mW/°C	377 mW
Р	1000 mW	8.0 mW/°C	520 mW
PW	525 mW	4.2 mW/°C	273 mW

#### recommended operating conditions

		MIN	MAX	UNIT
Supply voltage, V <sub>DD</sub>		2	8	V
Common-mode input voltage, V <sub>IC</sub>	V <sub>DD</sub> = 3 V	-0.2	1.8	V
	V <sub>DD</sub> = 5 V	-0.2	3.8	V
Operating free-air temperature, T <sub>A</sub>			85	°C



#### **HIGH-BIAS MODE**

#### electrical characteristics at specified free-air temperature

						TLV2	3411			
	PARAMETER	TEST CONDITIONS	T <sub>A</sub> †	V	DD = 3 \	/	٧	<sub>DD</sub> = 5 \	,	UNIT
				MIN	TYP	MAX	MIN	TYP	MAX	
VIO	Input offset voltage	V <sub>O</sub> = 1 V, V <sub>IC</sub> = 1 V,	25°C		0.6	8		1.1	8	mV
۷IO	input onset voltage	$R_S = 50 \Omega$ , $R_L = 10 \text{ k}\Omega$	Full range			10			10	IIIV
αVIO	Average temperature of input offset voltage		25°C to 85°C		2.7			2.7		μV/°C
lio	Input offset current (see Note 4)	V <sub>O</sub> = 1 V,	25°C		0.1			0.1		pА
טוי	input onset current (see Note 4)	V <sub>IC</sub> = 1 V	85°C		22	1000		24	1000	PΛ
lΒ	Input bias current (see Note 4)	V <sub>O</sub> = 1 V,	25°C		0.6			0.6		pА
.ID	input blue current (eee ricte 1)	V <sub>IC</sub> = 1 V	85°C		175	2000		200	2000	P/ \
			0500	-0.2	-0.3		-0.2	-0.3		V
	Common-mode input voltage range		25°C	to 2	to 2.3		to 4	to 4.2		ı v
VICR	(see Note 5)		Full range	-0.2 to 1.8			-0.2 to 3.8			V
		V <sub>IC</sub> = 1 V,	25°C	1.75	1.9		3.2	3.7		
VOH	High-level output voltage	$V_{ID} = 100 \text{ mV},$ $I_{OH} = -1 \text{ mA}$	Full range	1.7			3			V
.,		V <sub>IC</sub> = 1 V,	25°C		120	150		90	150	.,
VOL	Low-level output voltage	$V_{ID} = -100 \text{ mV},$ $I_{OL} = 1 \text{ mA}$	Full range			190			190	mV
	Large-signal differential	V <sub>IC</sub> = 1 V,	25°C	3	11		5	23		) //>/
AVD	voltage amplification	$R_L$ = 10 kΩ, See Note 6	Full range	2			3.5			V/mV
CMRR	Common mode valenties vatio	V <sub>O</sub> = 1 V,	25°C	65	78		65	80		dB
CIVIRR	Common-mode rejection ratio	$V_{IC} = V_{ICR}$ min, $R_S = 50 \Omega$	Full range	60			60			иь
kovis	Supply-voltage rejection ratio	V <sub>IC</sub> = 1 V, V <sub>O</sub> = 1 V,	25°C	70	95		70	95		ЧB
ksvr	$(\Delta V_{DD}/\Delta V_{IO})$	$V_0 = 1 V$ , $R_S = 50 \Omega$	Full range	65			65			dB
I <sub>I(SEL)</sub>	Bias select current	VI(SEL) = 0	25°C		-1.2			-1.4		μΑ
Inn	Supply current	V <sub>O</sub> = 1 V, V <sub>IC</sub> = 1 V,	25°C		325	1500		675	1600	μΑ
IDD	очрріу сипені	V <sub>I</sub> C = 1 V, No load	Full range			2000			2200	μΑ

† Full range is –40°C to 85°C.

NOTES: 4. The typical values of input bias current and input offset current below 5 pA are determined mathematically.

5. This range also applies to each input individually.

6. At V<sub>DD</sub> = 5 V, V<sub>O</sub> = 0.25 V to 2 V; at V<sub>DD</sub> = 3 V, V<sub>O</sub> = 0.5 V to 1.5 V.



#### **HIGH-BIAS MODE**

#### operating characteristics at specified free-air temperature, $V_{DD} = 3 V$

	DADAMETED	TEST	ONDITIONS	т.	TLV2341I			UNIT	
	PARAMETER	lesi c	CNDITIONS	TA	MIN	TYP	MAX	UNIT	
SR	Slew rate at unity gain	$V_{IC} = 1 V$ , $R_L = 10 \text{ k}\Omega$ ,	$V_{I(PP)} = 1 \text{ V},$	25°C		2.1		V/µs	
SK		See Figure 92	о_ = 20 рг,	85°C		1.7		ν/μδ	
Vn	Equivalent input noise voltage	f = kHz, See Figure 93	$R_S = 20 \Omega$ ,	25°C		25		nV/√ <del>Hz</del>	
D	Maximum autaut awing bandwidth	$V_O = V_{OH}$ , $R_L = 10 \text{ k}\Omega$ ,	C <sub>L</sub> = 20 pF,	25°C		170		kHz	
ВОМ	Maximum output-swing bandwidth		See Figure 92	85°C		145		KIIZ	
B <sub>1</sub>	Unity-gain bandwidth	V <sub>I</sub> = 10 mV,	C <sub>L</sub> = 20 pF,	25°C		790		kHz	
LP1	Offity-gairt baridwidth	$R_L = 10 \text{ k}\Omega$ ,	See Figure 94	85°C		690		NI 1Z	
		V <sub>I</sub> = 10 mV,	f = B <sub>1</sub> ,	-40°C		53°			
φm	Phase margin	$C_L = 20 \text{ pF},$	$R_L = 1 M\Omega$ ,	25°C		49°			
		See Figure 94		85°C		47°			

#### operating characteristics at specified free-air temperature, $V_{DD} = 5 \text{ V}$

	DADAMETED	TEST	CONDITIONS	т.	TLV2341I			UNIT	
	PARAMETER	TEST	CONDITIONS	TA	MIN	TYP	MAX	ONIT	
		V <sub>IC</sub> = 1 V,	V.(22) - 1 V	25°C		3.6			
SR	Slew rate at unity gain	$R_L = 10 \text{ k}\Omega$	V <sub>I(PP)</sub> = 1 V	85°C		2.8		\//	
SK	Siew rate at unity gain	$C_L = 20 \text{ pF},$	V((DD) - 2.5.V	25°C		2.9		V/μs	
		See Figure 92	V <sub>I(PP)</sub> = 2.5 V	85°C		2.3			
V <sub>n</sub>	Equivalent input noise voltage	f = 1 kHz, See Figure 93	$R_S = 20 \Omega$ ,	25°C		25		nV/√ <del>Hz</del>	
D	Maximum autaut auting handwidth	V <sub>O</sub> = V <sub>OH</sub> ,	$C_{I} = 20 \text{ pF},$	25°C		320		kHz	
ВОМ	Maximum output-swing bandwidth	$R_L = 10 \text{ k}\Omega$ ,	See Figure 92	85°C		250		KHZ	
р.	I laite agin handwidth	V <sub>I</sub> = 10 mV,	C <sub>L</sub> = 20 pF,	25°C		1.7		N 41 1-	
B <sub>1</sub>	Unity-gain bandwidth	$R_L = 10 \text{ k}\Omega$ ,	See Figure 94	85°C		1.2		MHz	
		V <sub>I</sub> = 10 mV,	f = B <sub>1</sub> ,	-40°C		49°			
φm	Phase margin	$C_L = 20 \text{ pF},$	$R_L = 10 \text{ k}\Omega$ ,	25°C		46°			
		See Figure 94		85°C		43°			



#### **HIGH-BIAS MODE**

#### electrical characteristics, $T_A = 25^{\circ}C$

					TLV2341I					
	PARAMETER	TEST C	ONDITIONS	V	DD = 3 \	1	VI	DD = 5 \	/	UNIT
				MIN	TYP	MAX	MIN	TYP	MAX	
VIO	Input offset voltage	$V_{O} = 1 V$ , $R_{S} = 50 \Omega$ ,	$V_{IC} = 1 V$ , $R_L = 10 k\Omega$		0.6	8		1.1	8	mV
I <sub>IO</sub>	Input offset current (see Note 4)	V <sub>O</sub> = 1 V,	V <sub>IC</sub> = 1 V		0.1			0.1		pА
I <sub>IB</sub>	Input bias current (see Note 4)	V <sub>O</sub> = 1 V,	V <sub>IC</sub> = 1 V		0.6			0.6		pА
VICR	Common-mode input voltage range (see Note 5)			-0.2 to 2	-0.3 to 2.3		-0.2 to 4	-0.3 to 4.2		V
VOH	High-level output voltage	V <sub>IC</sub> = 1 V, I <sub>OH</sub> = -1 mA	V <sub>ID</sub> = 100 mV,	1.75	1.9		3.2	3.7		V
V <sub>OL</sub>	Low-level output voltage	V <sub>IC</sub> = 1 V, I <sub>OL</sub> = 1 mA	$V_{ID} = -100 \text{ mV},$		120	150		90	150	mV
AVD	Large-signal differential voltage amplification	V <sub>IC</sub> = 1 V, See Note 6	$R_L = 10 \text{ k}\Omega$ ,	3	11		50	23		V/mV
CMRR	Common-mode rejection ratio	$V_O = 1 V$ , $R_S = 50 \Omega$	$V_{IC} = V_{ICR}min$ ,	65	78		65	80		dB
ksvr	Supply-voltage rejection ratio $(\Delta V_{DD}/\Delta V_{IO})$	$V_O = 1 V$ , $R_S = 50 \Omega$	V <sub>IC</sub> = 1 V,	70	95		70	95		dB
I <sub>I</sub> (SEL)	Bias select current	$V_{I(SEL)} = 0$			-1.2			-1.4		μΑ
I <sub>DD</sub>	Supply current	V <sub>O</sub> = 1 V, No load	V <sub>IC</sub> = 1 V,		325	1500		675	1600	μΑ

NOTES: 4. The typical values of input bias current and input offset current below 5 pA are determined mathematically.

5. This range also applies to each input individually.

6. At  $V_{DD} = 5 \text{ V}$ ,  $V_{O} = 0.25 \text{ V}$  to 2 V; at  $V_{DD} = 3 \text{ V}$ ,  $V_{O} = 0.5 \text{ V}$  to 1.5 V.

#### **Table of Graphs**

			FIGURE
VIO	Input offset voltage	Distribution	2,3
ανιο	Input offset voltage temperature coefficient	Distribution	4,5
Vон	High-level output voltage	vs Output current vs Supply voltage vs Temperature	6 7 8
VOL	Low-level output voltage	vs Common-mode input voltage vs Temperature vs Differential input voltage vs Low-level output current	9 10, 12 11 13
A <sub>VD</sub>	Large-signal differential voltage amplification	vs Supply voltage vs Temperature vs Frequency	14 15 26, 27
I <sub>IB</sub>	Input bias current	vs Temperature	16
lιο	Input offset current	vs Temperature	16
VIC	Common-mode input voltage	vs Supply voltage	17
IDD	Supply current	vs Supply voltage vs Temperature	18 19
SR	Slew rate	vs Supply voltage vs Temperature	20 21
	Bias select current	vs Supply voltage	22
V <sub>O(PP)</sub>	Maximum peak-to-peak output voltage	vs Frequency	23
B <sub>1</sub>	Unity-gain bandwidth	vs Temperature vs Supply voltage	24 25
φm	Phase margin	vs Supply voltage vs Temperature vs Load capacitance	28 29 30
Vn	Equivalent input noise voltage	vs Frequency	31
	Phase shift	vs Frequency	26, 27



#### **DISTRIBUTION OF TLV2341 INPUT OFFSET VOLTAGE**

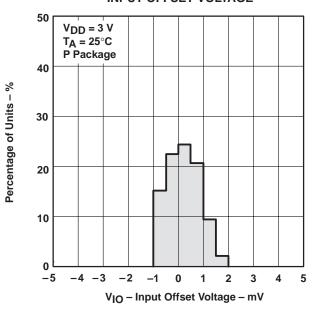
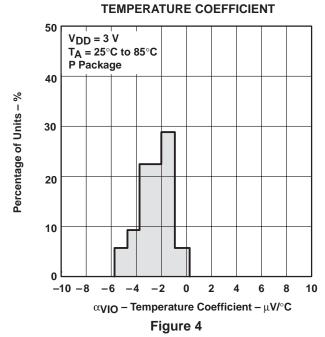


Figure 2

#### **DISTRIBUTION OF TLV2341 INPUT OFFSET VOLTAGE**



#### **DISTRIBUTION OF TLV2341 INPUT OFFSET VOLTAGE**

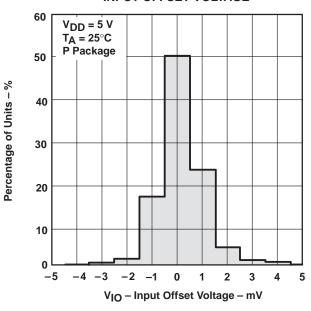
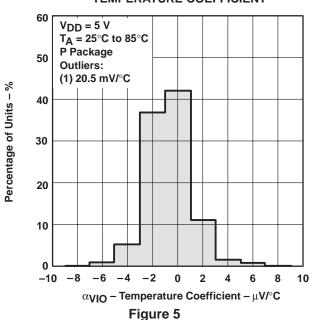
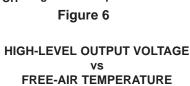


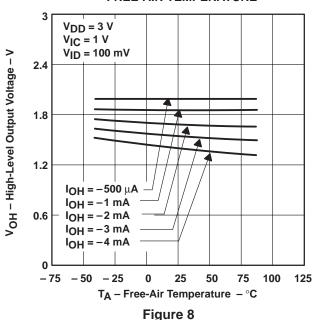
Figure 3

#### **DISTRIBUTION OF TLV2341 INPUT OFFSET VOLTAGE TEMPERATURE COEFFICIENT**

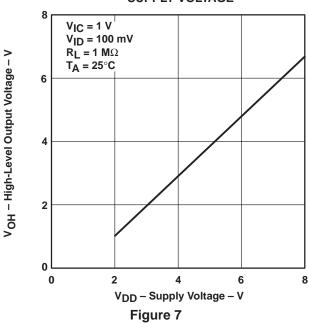


# HIGH-LEVEL OUTPUT CURRENT VIC = 1 V VIC = 1 V VID = 100 mV TA = 25°C VDD = 3 V VDD = 3 V IOH - High-Level Output Current - mA

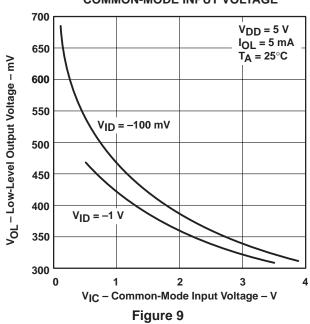




#### HIGH-LEVEL OUTPUT VOLTAGE vs SUPPLY VOLTAGE



# LOW-LEVEL OUTPUT VOLTAGE vs COMMON-MODE INPUT VOLTAGE

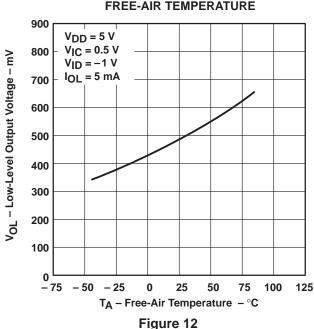




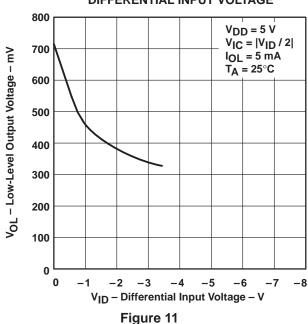
#### LOW-LEVEL OUTPUT VOLTAGE FREE-AIR TEMPERATURE 200 $V_{DD} = 3 V$ $V_{IC} = 1 V$ VOL - Low-Level Output Voltage - mV $V_{ID} = -100 \text{ mV}$ 185 IOL = 1 mA 150 125 100 75 50 - 75 - 50 - 25 0 25 50 75 100 125 $T_A$ – Free-Air Temperature – ${}^{\circ}C$

# LOW-LEVEL OUTPUT VOLTAGE vs FREE-AIR TEMPERATURE

Figure 10



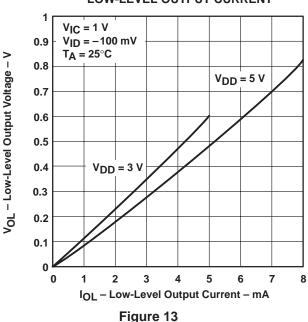
# LOW-LEVEL OUTPUT VOLTAGE vs DIFFERENTIAL INPUT VOLTAGE



LOW-LEVEL OUTPUT VOLTAGE

vs

LOW-LEVEL OUTPUT CURRENT



#### **LARGE-SIGNAL DIFFERENTIAL VOLTAGE AMPLIFICATION**

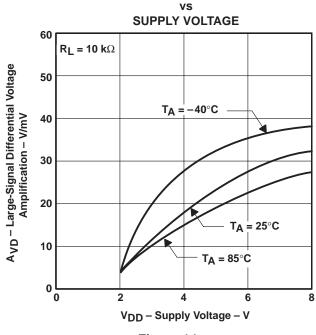


Figure 14

#### LARGE-SIGNAL **DIFFERENTIAL VOLTAGE AMPLIFICATION**

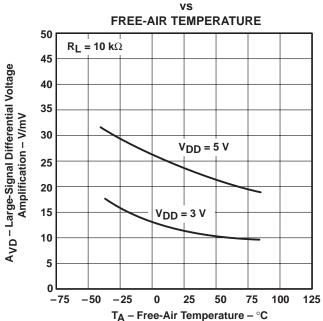
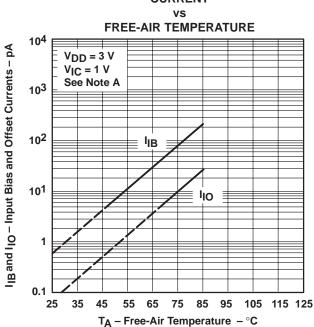


Figure 15

#### INPUT BIAS CURRENT AND INPUT OFFSET **CURRENT**



NOTE: The typical values of input bias current and input offset current below 5 pA were determined mathematically.

**COMMON-MODE INPUT VOLTAGE POSITIVE LIMIT** 

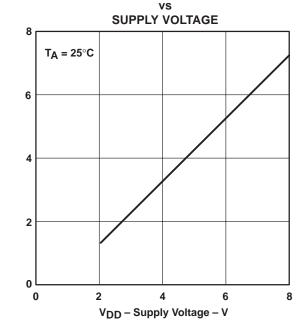
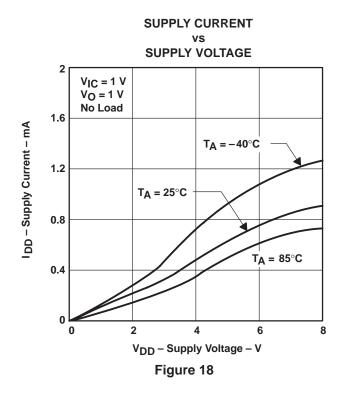


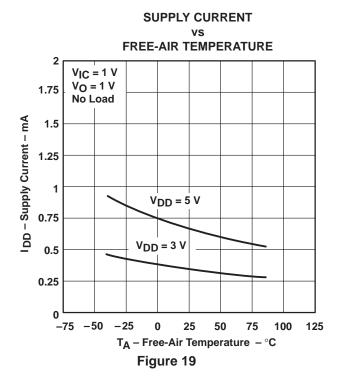
Figure 17

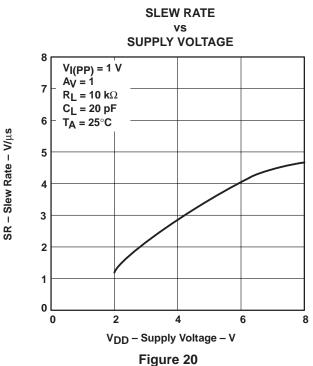
Figure 16

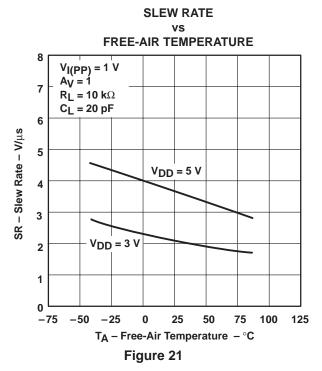
V<sub>IC</sub> - Common-Mode Input Voltage - V











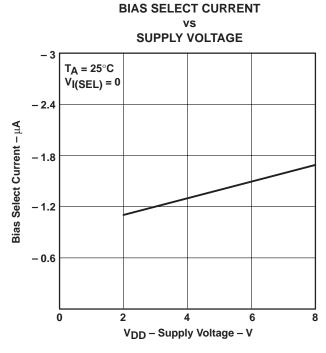


Figure 22

**UNITY-GAIN BANDWIDTH** 

#### FREE-AIR TEMPERATURE 3.5 $V_I = 10 \text{ mV}$ $R_L = 10 \text{ k}\Omega$ $C_{L}^{-} = 20 \text{ pF}$ B<sub>1</sub> – Unity-Gain Bandwidth – MHz 2.9 2.3 $V_{DD} = 5 V$ 1.7 1.1 $V_{DD} = 3 V$ 0.5 -75 -50 50 75 100 125 T<sub>A</sub> - Free-Air Temperature - °C Figure 24

# **MAXIMUM PEAK-TO-PEAK OUTPUT VOLTAGE FREQUENCY**

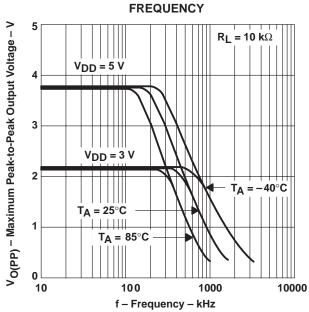
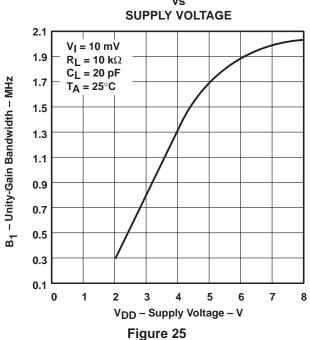


Figure 23

### **UNITY-GAIN BANDWIDTH**





## LARGE-SIGNAL DIFFERENTIAL VOLTAGE AMPLIFICATION AND PHASE SHIFT

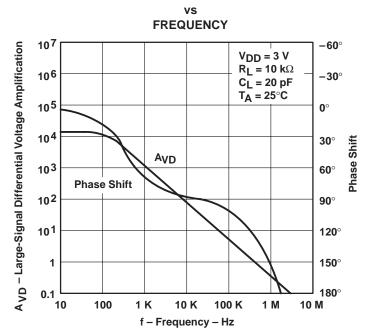


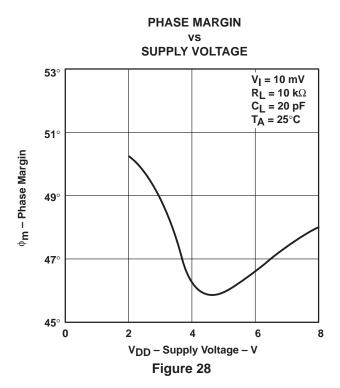
Figure 26

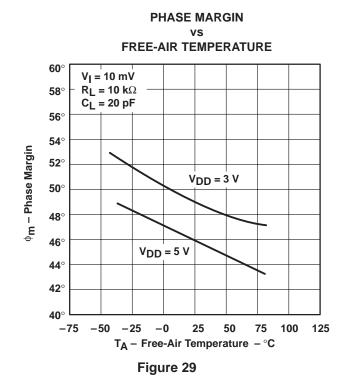
## LARGE-SIGNAL DIFFERENTIAL VOLTAGE AMPLIFICATION AND PHASE SHIFT

**FREQUENCY** 107 -60° A<sub>VD</sub> - Large-Signal Differential Voltage Amplification  $V_{DD} = 5 V$  $R_L = 10 \text{ k}\Omega$ 10<sup>6</sup> -30°  $C_{L}^{-} = 20 \text{ pF}$  $T_A = 25^{\circ}C$ 105 **0**° 104 Phase Shift **30**° AVD 103 60° 102 90° **Phase Shift** 101 120° 1 150° 0.1 180° 100 10 k 1 M 10 M 10 1 k 100 k f - Frequency - Hz

Figure 27







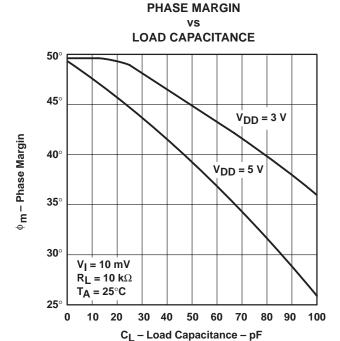
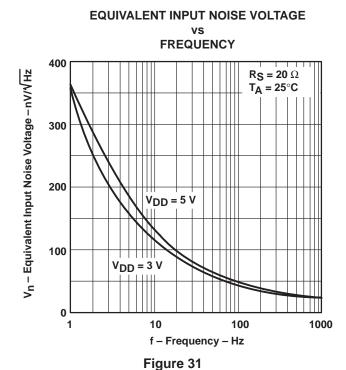


Figure 30



#### **MEDIUM-BIAS MODE**

#### electrical characteristics at specified free-air temperature

						TLV2	341I			
	PARAMETER	TEST CONDITIONS	T <sub>A</sub> †	V	DD = 3 \	/	٧	<sub>DD</sub> = 5 \	,	UNIT
		CONDITIONS		MIN	TYP	MAX	MIN	TYP	MAX	
.,		$V_{O} = 1 V,$ $V_{IC} = 1 V,$	25°C		0.6	8		1.1	8	.,
VIO	Input offset voltage	$R_S = 50 \Omega$ , $R_L = 100 \text{ k}\Omega$	Full range			10			10	mV
ανιο	Average temperature coefficient of input offset voltage		25°C to 85°C		1			1.7		μV/°C
li o	Input offset current (see Note 4)	V <sub>O</sub> = 1 V,	25°C		0.1			0.1		pА
ΙO	input onset current (see Note 4)	V <sub>IC</sub> = 1 V	85°C		22	1000		24	1000	PΑ
I <sub>IB</sub>	Input bias current (see Note 4)	V <sub>O</sub> = 1 V,	25°C		0.6			0.6		pА
'ID	mpat blas darrent (see Note 4)	V <sub>IC</sub> = 1 V	85°C		175	2000		200	2000	
			0500	-0.2	-0.3		-0.2	-0.3		.,
	Common-mode input voltage range		25°C	to 2	to 2.3		to 4	to 4.2		V
VICR	Common-mode input voltage range (see Note 5)			-0.2			-0.2			
	,		Full range	to			to			V
				1.8			3.8			
	High-level output voltage	V <sub>IC</sub> = 1 V,	25°C	1.75	1.9		3.2	3.9		
VOH		$V_{ID} = 100 \text{ mV},$ $I_{OH} = -1 \text{ mA}$	Full range	1.7			3			V
.,	Law law Law to take the se	V <sub>IC</sub> = 1 V,	25°C		115	150		95	150	>/
VOL	Low-level output voltage	$V_{ID} = -100 \text{ mV},$ $I_{OL} = 1 \text{ mA}$	Full range			190			190	mV
Λ	Large-signal differential	$V_{IC} = 1 \text{ V},$ $R_{I} = 100 \text{ k}\Omega,$	25°C	25	83		25	170		V/mV
AVD	voltage amplification	See Note 6	Full range	15			15			V/IIIV
CMRR	Common-mode rejection ratio	$V_O = 1 V$ , $V_{IC} = V_{ICR}min$ ,	25°C	65	92		65	91		dB
CIVIRK	Common-mode rejection ratio	$R_S = 50 \Omega$	Full range	60			60			uБ
leas ea	Supply-voltage rejection ratio	V <sub>IC</sub> = 1 V,	25°C	70	94		70	94		ďD
ksvr	$(\Delta V_{DD}/\Delta V_{IO})$	$V_O = 1 V$ , $R_S = 50 \Omega$	Full range	65			65			dB
I <sub>I</sub> (SEL)	Bias select current	VI(SEL) = 0	25°C		-100			-130		nA
1	Cumply ourrant	V <sub>O</sub> = 1 V, V <sub>IC</sub> = 1 V,	25°C		65	250		105	280	4
IDD	Supply current	No load	Full range			360			400	μΑ

<sup>†</sup>Full range is -40°C to 85°C.

NOTES: 4. The typical values of input bias current and input offset current below 5 pA are determined mathematically.

- 5. This range also applies to each input individually.
- 6. At  $V_{DD} = 5 \text{ V}$ ,  $V_{O} = 0.25 \text{ V}$  to 2 V; at  $V_{DD} = 3 \text{ V}$ ,  $V_{O} = 0.5 \text{ V}$  to 1.5 V.



#### **MEDIUM-BIAS MODE**

### operating characteristics at specified free-air temperature, $V_{DD} = 3 V$

PARAMETER		TEST CO	NDITIONS	TA	TLV2341I			UNIT					
	PARAMETER	1251 CO	TEST CONDITIONS		MIN	TYP	MAX	UNIT					
SR	$V_{IC}$ = 1 V, $V_{I(PP)}$ = 1 V, $R_L$ = 100 kΩ, $C_L$ = 20 pF, See Figure 92		25°C		0.38		V/µs						
SIX					85°C		0.29		ν/μδ				
V <sub>n</sub>	Equivalent input noise voltage	f = kHz, See Figure 93	$R_S = 20 \Omega$ ,	25°C		32		nV/√ <del>Hz</del>					
Para	Maximum output-swing bandwidth	$V_O = V_{OH}$	C <sub>L</sub> = 20 pF,	25°C		34		kHz					
Вом	Maximum output-swing bandwidth	$R_L = 100 \text{ k}\Omega$ ,	$R_L = 100 \text{ k}\Omega$ ,	$R_L = 100 \text{ k}\Omega$ ,	$R_L = 100 \text{ k}\Omega$ ,	$R_L = 100 \text{ k}\Omega$ ,	$R_L = 100 \text{ k}\Omega$ ,	See Figure 92	85°C		32		KIIZ
B <sub>1</sub>	Unity-gain bandwidth	V <sub>I</sub> = 10 mV,	C <sub>L</sub> = 20 pF,	25°C		300		kHz					
LP1	Onity-gain bandwidth	$R_L = 100 \text{ k}\Omega$ ,	$L = 100 \text{ k}\Omega$ , See Figure 94			235		KI IZ					
		$V_{I} = 10 \text{ mV},  f = B_{1},$		V <sub>I</sub> = 10 mV. f = B <sub>1</sub> .	-40°C		42°						
φm	Phase margin	$C_L = 20 pF$ ,		25°C		39°							
		See Figure 94		85°C		36°							

#### operating characteristics at specified free-air temperature, $V_{DD} = 5 \text{ V}$

	PARAMETER		NDITIONS	TA	TLV2341I			UNIT													
	PARAMETER	1231 00	TEST CONDITIONS			TYP	MAX	ONIT													
	$V_{IC} = 1 \text{ V},  V_{I}$		Vic	V <sub>1</sub> (22) = 1 V	25°C		0.43														
SR	Slow rate of unity gain	$R_L = 100 \text{ k}Ω$ , $C_L = 20 \text{ pF}$ ,	V <sub>I(PP)</sub> = 1 V	85°C		0.35		V/µs													
J SK	Slew rate at unity gain		V() 2.5.V	25°C		0.40		ν/μ5													
			$V_{I(PP)} = 2.5 V$	85°C		0.32															
Vn	Equivalent input noise voltage	f =1 kHz, See Figure 93	$R_S = 20 \Omega$ ,	25°C		32		nV/√ <del>Hz</del>													
D	Maximum autout auting handwidth	$V_O = V_{OH}$ , $R_L = 100 \text{ k}\Omega$ ,	$C_{I} = 20 \text{ pF},$	25°C		55		kHz													
ВОМ	Maximum output-swing bandwidth			$R_L = 100 \text{ k}\Omega$ ,	$R_L = 100 \text{ k}\Omega$ ,	$R_L = 100 \text{ k}\Omega$				$R_L = 100 \text{ k}\Omega$ ,	$R_L = 100 \text{ k}\Omega$ ,	$R_L = 100 \text{ k}\Omega$	$R_L = 100 \text{ k}\Omega$		$R_L = 100 \text{ k}\Omega$	$R_L = 100 \text{ k}\Omega$ ,	See Figure 92	85°C		45	
В.	Unity agin bonduidth	V <sub>I</sub> = 10 mV,	C <sub>L</sub> = 20 pF,	25°C		525		kHz													
B <sub>1</sub>	Unity-gain bandwidth	$R_L$ = 100 kΩ,	See Figure 94	85°C		370		KHZ													
	V <sub>I</sub> = 10 mV,		f = B <sub>1</sub> ,	-40°C		43°															
φm	Phase margin			$C_L = 20 \text{ pF}, R$			25°C		40°												
				85°C		38°															



#### **MEDIUM-BIAS MODE**

#### electrical characteristics, $T_A = 25^{\circ}C$

						TLV2	3411			
	PARAMETER		TEST CONDITIONS		V <sub>DD</sub> = 3 V		V <sub>DD</sub> = 5 V			UNIT
				MIN	TYP	MAX	MIN	TYP	MAX	
VIO	Input offset voltage	$V_O = 1 V$ , $R_S = 50 \Omega$ ,	$V_{IC} = 1 V$ , $R_L = 100 k\Omega$		0.6	8		1.1	8	mV
I <sub>IO</sub>	Input offset current (see Note 4)	V <sub>O</sub> = 1 V,	V <sub>IC</sub> = 1 V		0.1			0.1		pА
I <sub>IB</sub>	Input bias current (see Note 4)	V <sub>O</sub> = 1 V,	V <sub>IC</sub> = 1 V		0.6			0.6		pА
VICR	Common-mode input voltage range (see Note 5)			-0.2 to 2	-0.3 to 2.3		-0.2 to 4	-0.3 to 4.2		V
VOH	High-level output voltage	$V_{IC} = 1 V$ , $I_{OH} = -1 \text{ mA}$	V <sub>ID</sub> = 100 mV,	1.75	1.9		3.2	3.9		٧
VOL	Low-level output voltage	V <sub>IC</sub> = 1 V, I <sub>OL</sub> = 1 mA	$V_{ID} = -100 \text{ mV},$		115	150		95	150	mV
A <sub>VD</sub>	Large-signal differential voltage amplification	V <sub>IC</sub> = 1 V, See Note 6	$R_L = 100 \text{ k}\Omega$ ,	25	83		25	170		V/mV
CMRR	Common-mode rejection ratio	$V_O = 1 V$ , $R_S = 50 \Omega$	$V_{IC} = V_{ICR}min,$	65	92		65	91		dB
ksvr	Supply-voltage rejection ratio $(\Delta V_{DD}/\Delta V_{ID})$	$V_O = 1 V$ , $R_S = 50 \Omega$	V <sub>IC</sub> = 1 V,	70	94		70	94		dB
I(SEL)	Bias select current	V <sub>I(SEL)</sub> = 0			-100			-130		nA
IDD	Supply current	V <sub>O</sub> = 1 V, No load	V <sub>IC</sub> = 1 V,		65	250		105	280	μΑ

NOTES: 4. The typical values of input bias current and input offset current below 5 pA are determined mathematically.

5. This range also applies to each input individually. 6. At  $V_{DD} = 5$  V,  $V_{O} = 0.25$  V to 2 V; at  $V_{DD} = 3$  V,  $V_{O} = 0.5$  V to 1.5 V.

#### **Table of Graphs**

			FIGURE
VIO	Input offset voltage	Distribution	32, 33
ανιο	Input offset voltage temperature coefficient	Distribution	34, 35
Vон	High-level output voltage	vs Output current vs Supply voltage vs Temperature	36 37 38
VOL	Low-level output voltage	vs Common-mode input voltage vs Temperature vs Differential input voltage vs Low-level output current	39 40, 42 41 43
AVD	Large-signal differential voltage amplification	vs Supply voltage vs Temperature vs Frequency	44 45 56, 57
$I_{IB}$	Input bias current	vs Temperature	46
lio	Input offset current	vs Temperature	46
VIC	Common-mode input voltage	vs Supply voltage	47
IDD	Supply current	vs Supply voltage vs Temperature	48 49
SR	Slew rate	vs Supply voltage vs Temperature	50 51
	Bias select current	vs Supply current	52
V <sub>O(PP)</sub>	Maximum peak-to-peak output voltage	vs Frequency	53
B <sub>1</sub>	Unity-gain bandwidth	vs Temperature vs Supply voltage	54 55
фm	Phase margin	vs Supply voltage vs Temperature vs Load capacitance	58 59 60
Vn	Equivalent input noise voltage	vs Frequency	61
	Phase shift	vs Frequency	56, 57



## DISTRIBUTION OF TLV2341 INPUT OFFSET VOLTAGE

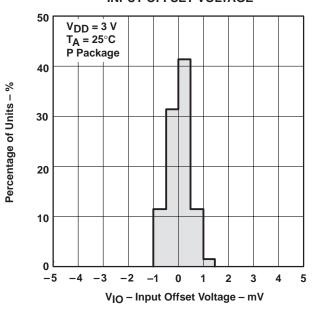
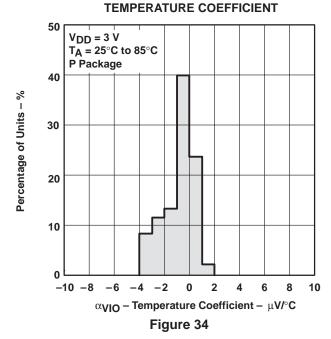


Figure 32

#### DISTRIBUTION OF TLV2341 INPUT OFFSET VOLTAGE



## DISTRIBUTION OF TLV2341 INPUT OFFSET VOLTAGE

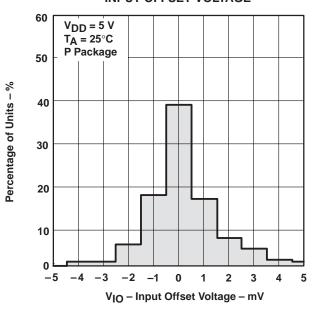
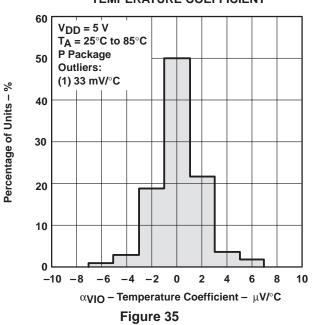


Figure 33

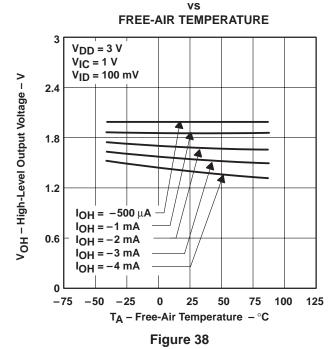
#### DISTRIBUTION OF TLV2341 INPUT OFFSET VOLTAGE TEMPERATURE COEFFICIENT



# HIGH-LEVEL OUTPUT CURRENT S HIGH-LEVEL OUTPUT CURRENT V<sub>IC</sub> = 1 V V<sub>ID</sub> = 100 mV T<sub>A</sub> = 25°C V<sub>DD</sub> = 5 V V<sub>DD</sub> = 5 V I<sub>OH</sub> - High-Level Output Current - mA

HIGH-LEVEL OUTPUT VOLTAGE

Figure 36



HIGH-LEVEL OUTPUT VOLTAGE
vs
SUPPLY VOLTAGE

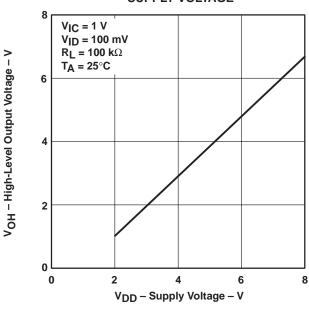


Figure 37

# LOW-LEVEL OUTPUT VOLTAGE vs COMMON-MODE INPUT VOLTAGE

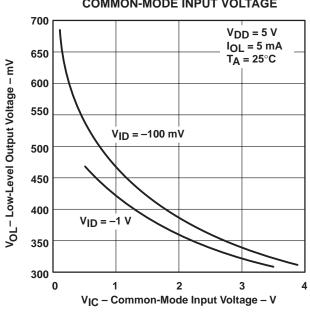


Figure 39

#### LOW-LEVEL OUTPUT VOLTAGE FREE-AIR TEMPERATURE 200 $V_{DD} = 3 V$ V<sub>IC</sub> = 1 V 185 $V_{ID} = -100 \text{ mV}$ V<sub>OL</sub>- Low-Level Output Voltage - mV IOL = 1 mA 170 155 140 125 110 95 80 65 50 -75 -50 -25 0 25 50 75 100 125 $T_A$ – Free-Air Temperature – ${}^{\circ}C$

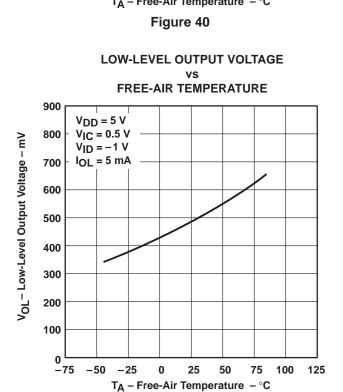
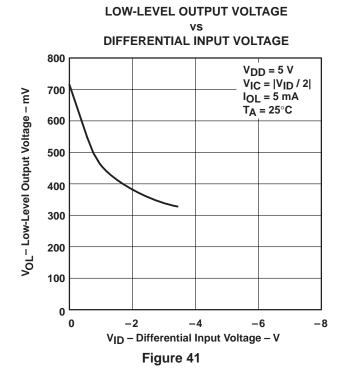
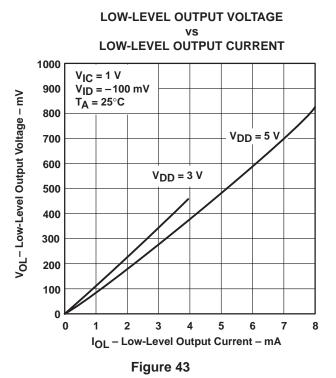
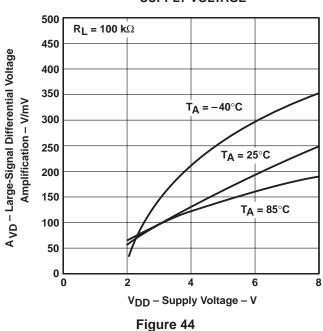


Figure 42





# LARGE-SIGNAL DIFFERENTIAL VOLTAGE AMPLIFICATION vs SUPPLY VOLTAGE



# LARGE-SIGNAL DIFFERENTIAL VOLTAGE AMPLIFICATION vs

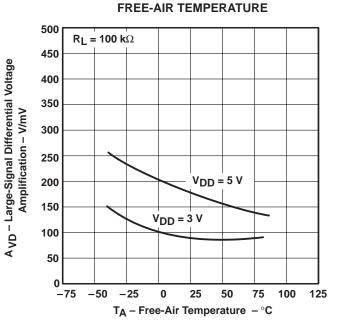
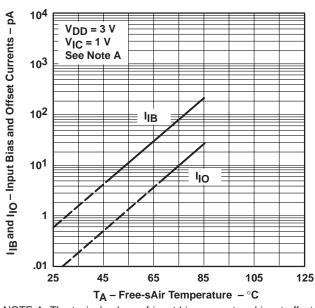


Figure 45

#### INPUT BIAS CURRENT AND INPUT OFFSET CURRENT

#### FREE-AIR TEMPERATURE



NOTE A: The typical values of input bias current and input offset current below 5 pA are determined mathematically.

Figure 46

#### COMMON-MODE INPUT VOLTAGE POSITIVE LIMIT

#### SUPPLY VOLTAGE

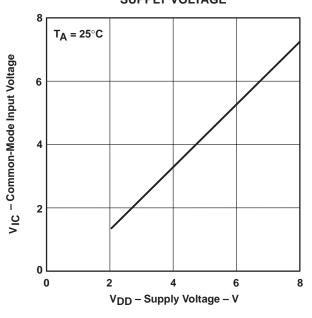
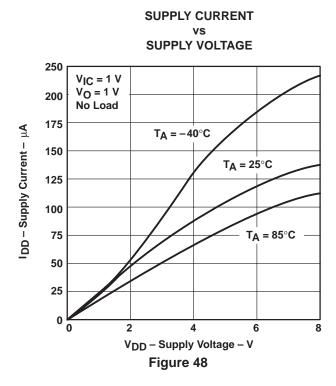
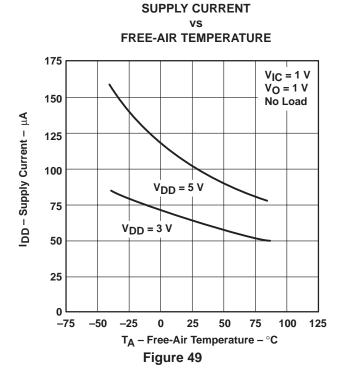
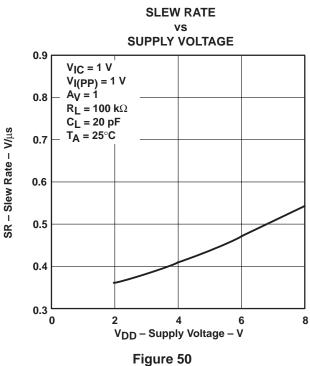


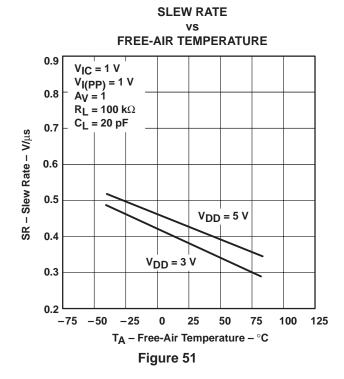
Figure 47











#### **BIAS SELECT CURRENT SUPPLY VOLTAGE** -300T<sub>A</sub> = 25°C $V_{I(SEL)} = 1/2 V_{DD}$ -270- 240 Bias Select Current - nA - 210 - 180 - 150 -120- 90 - 60 -300 o' 2 V<sub>DD</sub> - Supply Voltage - V

Figure 52

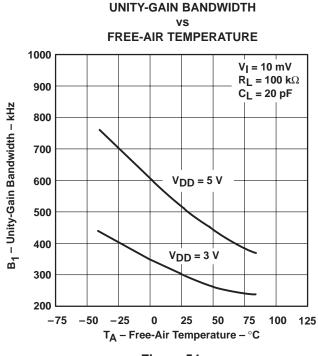


Figure 54

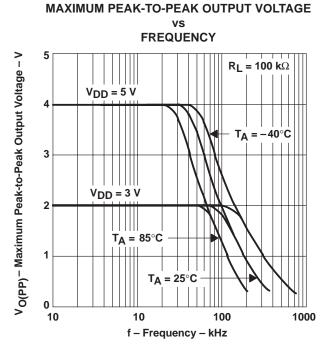
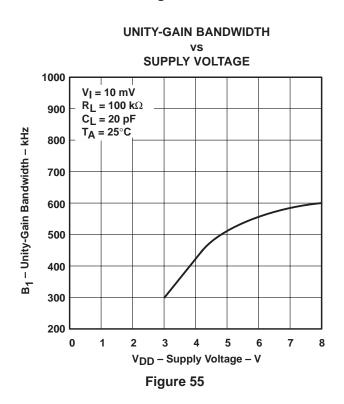


Figure 53





## LARGE-SIGNAL DIFFERENTIAL VOLTAGE AMPLIFICATION AND PHASE SHIFT

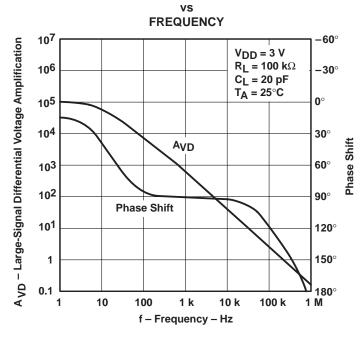


Figure 56

## LARGE-SIGNAL DIFFERENTIAL VOLTAGE AMPLIFICATION AND PHASE SHIFT

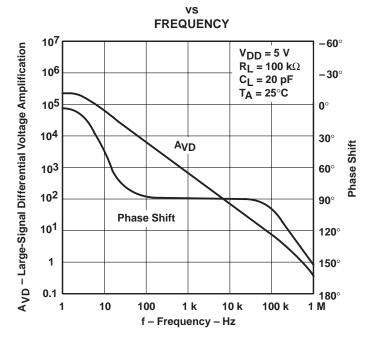
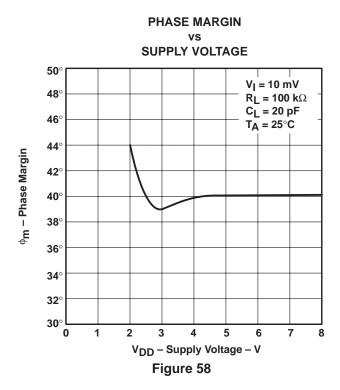
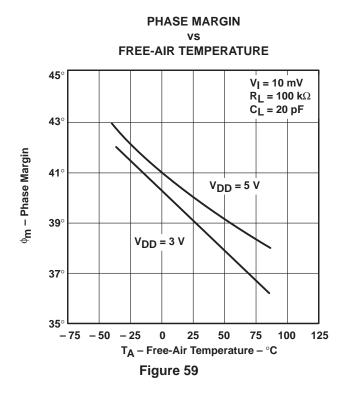
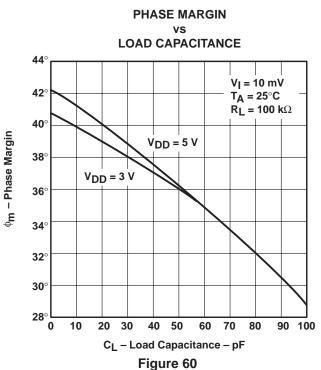


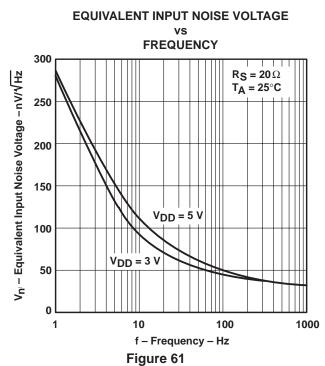
Figure 57











#### **LOW-BIAS MODE**

#### electrical characteristics at specified free-air temperature

						TLV2	3411			
PARAMETER		TEST CONDITIONS	T <sub>A</sub> †	V	DD = 3 \	/	V	DD = 5 V	,	UNIT
		CONDITIONS		MIN	TYP	MAX	MIN	TYP	MAX	
\/. <b>-</b>	Input offeet voltage	V <sub>O</sub> = 1 V, V <sub>IC</sub> = 1 V,	25°C		0.6	8		1.1	8	mV
VIO	Input offset voltage	$R_S = 50 \Omega$ , $R_L = 1 M\Omega$	Full range			10			10	mv
αΛΙΟ	Average temperature of input offset voltage		25°C to 85°C		1			1.1		μV/°C
1	Input offect current (see Note 4)	V <sub>O</sub> = 1 V,	25°C		0.1			0.1		- A
lo	Input offset current (see Note 4)	V <sub>IC</sub> = 1 V	85°C		22	1000		24	1000	pА
lin	Input bias current (see Note 4)	V <sub>O</sub> = 1 V,	25°C		0.6			0.6		pА
lΒ	input bias current (see Note 4)	V <sub>IC</sub> = 1 V	85°C		175	2000		200	2000	PΑ
V	Common-mode input		25°C	-0.2 to 2	-0.3 to 2.3		-0.2 to 4	-0.3 to 4.2		٧
VICR voltage range (see Note 5)		Full range	-0.2 to 1.8			-0.2 to 3.8			V	
		V <sub>IC</sub> = 1 V,	25°C	1.75	1.9		3.2	3.8		
VOH	High-level output voltage	$V_{ID} = 100 \text{ mV},$ $I_{OH} = -1 \text{ mA}$	Full range	1.7			3			V
Vol	Low-level output voltage	$V_{IC} = 1 \text{ V},$ $V_{ID} = -100 \text{ mV},$	25°C		115	150		95	150	mV
VOL	Zow love, output voltage	I <sub>OL</sub> = 1 mA	Full range			190			190	
AVD	Large-signal differential	$V_{IC} = 1 V$ , $R_{I} = 1 M\Omega$ ,	25°C	50	400		50	520		V/mV
7.00	voltage amplification	See Note 6	Full range	50			50			V/111V
CMRR	Common-mode rejection ratio	V <sub>O</sub> = 1 V, V <sub>IC</sub> = V <sub>ICR</sub> min,	25°C	65	88		65	94		dB
Civilata	Common-mode rejection ratio	$R_S = 50 \Omega$	Full range	60			60			ub
kovp	Supply-voltage rejection ratio	V <sub>IC</sub> = 1 V, V <sub>O</sub> = 1 V,	25°C	70	86		70	86		dB
ksvr	$(\Delta V_{DD}/\Delta V_{IO})$	$R_S = 50 \Omega$	Full range	65			65			uD
I <sub>I</sub> (SEL)	Bias select current	VI(SEL) = 0	25°C		10			65		nA
lDD	Supply current	V <sub>O</sub> = 1 V, V <sub>IC</sub> = 1 V,	25°C		5	17		10	17	μΑ
טט.		No load	Full range			27			27	μι (

<sup>†</sup> Full range is –40°C to 85°C.

NOTES: 4. The typical values of input bias current and input offset current below 5 pA are determined mathematically.

- 5. This range also applies to each input individually.
- 6. At  $V_{DD} = 5 \text{ V}$ ,  $V_{O(PP)} = 0.25 \text{ V}$  to 2 V; at  $V_{DD} = 3 \text{ V}$ ,  $V_{O} = 0.5 \text{ V}$  to 1.5 V.



#### **LOW-BIAS MODE**

#### operating characteristics at specified free-air temperature, $V_{DD} = 3 V$

PARAMETER		TEST CO	NDITIONS	т.	Т	LV2341I		UNIT					
	PARAMETER	TEST CO	NDITIONS	TA	MIN	TYP	MAX	UNIT					
SR	Slew rate at unity gain	$V_{IC} = 1 V$ , $R_{I} = 1 M\Omega$ ,	$V_{IC} = 1 \text{ V},$ $V_{I(PP)} = 1 \text{ V},$ $R_{L} = 1 \text{ M}\Omega,$ $C_{L} = 20 \text{ pF},$			0.02		V/µs					
J N	Siew rate at unity gain	See Figure 92				85°C		0.02		ν/μδ			
Vn	Equivalent input noise voltage	f = kHz, See Figure 93	$R_S = 20 \Omega$ ,	25°C		68		nV/√ <del>Hz</del>					
Para	Maximum output-swing bandwidth	$V_O = V_{OH},$ $R_L = 1 M\Omega,$			C <sub>L</sub> = 20 pF,	25°C		2.5		kHz			
ВОМ	Maximum output-swing bandwidth				$R_L = 1 M\Omega$ ,	$R_L = 1 M\Omega$ ,	$R_L = 1 M\Omega$ ,	$R_L = 1 M\Omega$ ,	$R_L = 1 M\Omega$ ,	$R_L = 1 M\Omega$ , S	See Figure 92	85°C	
B <sub>1</sub>	Unity-gain bandwidth	V <sub>I</sub> = 10 mV,	C <sub>L</sub> = 20 pF,	25°C		27		kHz					
P1	Onity-gain bandwidth	$R_L = 1 M\Omega$ ,	See Figure 94	85°C		21		KI IZ					
		V <sub>I</sub> = 10 mV,	f = B <sub>1</sub> ,	-40°C		39°							
φm	Phase margin	$C_{L} = 20 \text{ pF},$		$R_L = 1 M\Omega$ ,	25°C		34°						
	See Figure 94			85°C		28°							

#### operating characteristics at specified free-air temperature, $V_{DD} = 5 V$

	PARAMETER	TEST CO.	NDITIONS	TA	TLV2341I			UNIT				
	TANAMETEN		TEST CONDITIONS			TYP	MAX	UNII				
		V <sub>IC</sub> = 1 V,	V <sub>1</sub> (22) = 1 V	25°C		0.03						
SR	Slew rate at unity gain	$R_L = 1 M\Omega$ ,	V <sub>I(PP)</sub> = 1 V	85°C		0.03		\//uo				
SK	$C_L = 20 \text{ pF},$		$C_L = 20 \text{ pF},$	V((DD) = 2.5.V	25°C		0.03		V/μs			
	See Figure 92		$V_{I(PP)} = 2.5 V$	85°C		0.02						
V <sub>n</sub>	Equivalent input noise voltage	f =1 kHz, See Figure 93	$R_S = 20 \Omega$ ,	25°C		68		nV/√ <del>Hz</del>				
P	Maximum output awing handwidth	$V_O = V_{OH}$ , $R_L = 1 M\Omega$ ,		C <sub>L</sub> = 20 pF,	25°C		5		kHz			
BOM	Maximum output-swing bandwidth								See Figure 92	85°C		4
В.	Llaite, gain handwidth	V <sub>I</sub> = 10 mV,	C <sub>L</sub> = 20 pF,	25°C		85		kHz				
B <sub>1</sub>	Unity-gain bandwidth	$R_L = 1 M\Omega$ ,	See Figure 94	85°C		55		KHZ				
		V <sub>I</sub> = 10 mV,		-40°C		38°						
φm	Phase margin	C <sub>L</sub> = 20 pF, See Figure 94	$f = B_1$ , $R_L = 1 M\Omega$ ,	25°C		34°						
				85°C		28°						



#### **LOW-BIAS MODE**

#### electrical characteristics, $T_A = 25^{\circ}C$

				TLV2341Y						
PARAMETER		TEST COM	TEST CONDITIONS		V <sub>DD</sub> = 3 V		V <sub>DD</sub> = 5 V			UNIT
				MIN	TYP	MAX	MIN	TYP	MAX	
VIO	Input offset voltage	$V_O = 1 V$ , $R_S = 50 \Omega$ ,	$V_{IC} = 1 V$ , $R_L = 1 M\Omega$		0.6	8		1.1	8	mV
I <sub>IO</sub>	Input offset current (see Note 4)	V <sub>O</sub> = 1 V,	V <sub>IC</sub> = 1 V		0.1			0.1		рА
I <sub>IB</sub>	Input bias current (see Note 4)	V <sub>O</sub> = 1 V,	V <sub>IC</sub> = 1 V		0.6			0.6		рА
VICR	Common-mode input voltage range (see Note 5)			-0.2 to 2	-0.3 to 2.3		-0.2 to 4	-0.3 to 4.2		V
VOH	High-level output voltage	V <sub>IC</sub> = 1 V, I <sub>OH</sub> = -1 mA	V <sub>ID</sub> = 100 mV,	1.75	1.9		3.2	3.8		V
VOL	Low-level output voltage	V <sub>IC</sub> = 1 V, I <sub>OL</sub> = 1 mA	$V_{ID} = -100 \text{ mV},$		115	150		95	150	mV
AVD	Large-signal differential voltage amplification	V <sub>IC</sub> = 1 V, See Note 6	$R_L = 1 M\Omega$ ,	50	400		50	520		V/mV
CMRR	Common-mode rejection ratio	$V_O = 1 V$ , $R_S = 50 \Omega$	$V_{IC} = V_{ICR}min,$	65	88		65	94		dB
k <sub>SVR</sub>	Supply-voltage rejection ratio $(\Delta V_{DD}/\Delta V_{ID})$	$V_{DD} = 3 \text{ V to 5 V},$ $V_{O} = 1 \text{ V},$	$V_{IC} = 1 V$ , $R_S = 50 \Omega$	70	86		70	86		dB
I <sub>I</sub> (SEL)	Bias select current	V <sub>I</sub> (SEL) = 0			10			65		nA
IDD	Supply current	V <sub>O</sub> = 1 V, No load	V <sub>IC</sub> = 1 V,		5	17		10	17	μΑ

NOTES: 4. The typical values of input bias current and input offset current below 5 pA are determined mathematically.

5. This range also applies to each input individually.

6. At  $V_{DD}$  = 5 V,  $V_{O}$  = 0.25 V to 2 V; at  $V_{DD}$  = 3 V,  $V_{O}$  = 0.5 V to 1.5 V.

#### **Table of Graphs**

			FIGURE
VIO	Input offset voltage	Distribution	62, 63
ανιο	Input offset voltage temperature coefficient	Distribution	64, 65
Vон	High-level output voltage	vs Output current vs Supply voltage vs Temperature	66 67 68
VOL	Low-level output voltage	vs Common-mode input voltage vs Temperature vs Differential input voltage vs Low-level output current	69 70, 72 71 73
A <sub>VD</sub>	Large-signal differential voltage amplification	vs Supply voltage vs Temperature vs Frequency	74 75 86, 87
I <sub>IB</sub>	Input bias current	vs Temperature	76
lio	Input offset current	vs Temperature	76
VIС	Common-mode input voltage	vs Supply voltage	77
IDD	Supply current	vs Supply voltage vs Temperature	78 79
SR	Slew rate	vs Supply voltage vs Temperature	80 81
	Bias select current	vs Supply current	82
V <sub>O(PP)</sub>	Maximum peak-to-peak output voltage	vs Frequency	83
B <sub>1</sub>	Unity-gain bandwidth	vs Temperature vs Supply voltage	84 85
φm	Phase margin	vs Supply voltage vs Temperature vs Load capacitance	88 89 90
Vn	Equivalent input noise voltage	vs Frequency	91
	Phase shift	vs Frequency	86, 87



**DISTRIBUTION OF TLV2341** 

**INPUT OFFSET VOLTAGE** 

#### **TYPICAL CHARACTERISTICS (LOW-BIAS MODE)**

## DISTRIBUTION OF TLV2341 INPUT OFFSET VOLTAGE

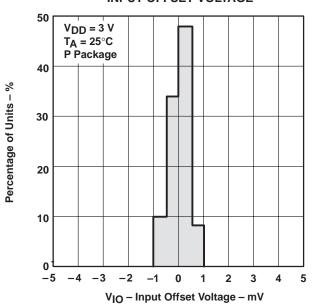


Figure 62

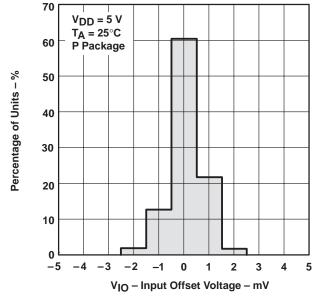
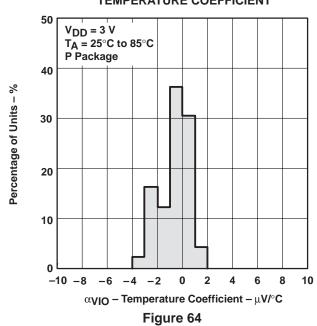
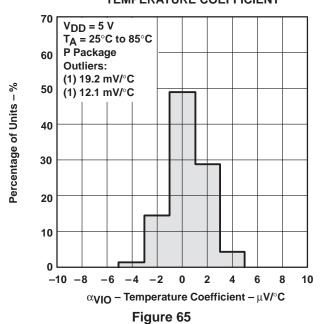


Figure 63

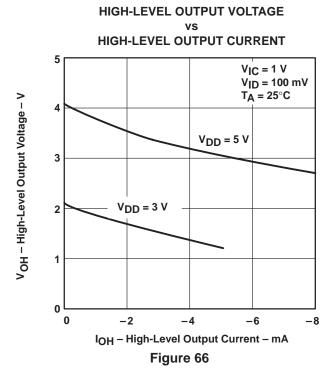
#### DISTRIBUTION OF TLV2341 INPUT OFFSET VOLTAGE TEMPERATURE COEFFICIENT



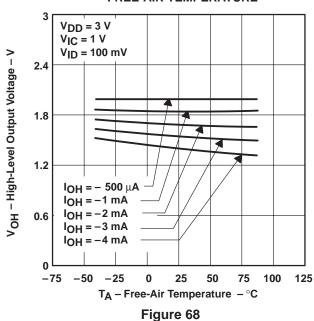
#### DISTRIBUTION OF TLV2341 INPUT OFFSET VOLTAGE TEMPERATURE COEFFICIENT



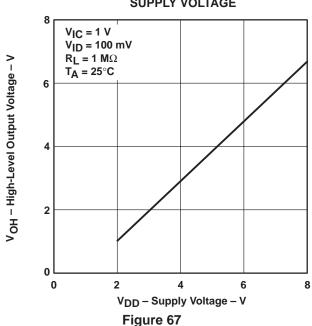




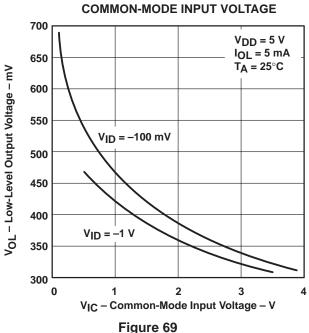




HIGH-LEVEL OUTPUT VOLTAGE
vs
SUPPLY VOLTAGE



# LOW-LEVEL OUTPUT VOLTAGE VS COMMON-MODE INPUT VOLTAGE



**LOW-LEVEL OUTPUT VOLTAGE** 

### TYPICAL CHARACTERISTICS (LOW-BIAS MODE)

0

0

-2

# LOW-LEVEL OUTPUT VOLTAGE VS FREE-AIR TEMPERATURE VDD = 3 V VIC = 1 V VID = -100 mV IOL = 1 mA

200

185

170

155

140 125

110

95

80

65 50

-75

-50

-25

0

V<sub>OL</sub> - Low-Level Output Voltage - mV

LOW-LEVEL OUTPUT VOLTAGE
vs
FREE-AIR TEMPERATURE

25

 $T_A$  – Free-Air Temperature –  ${}^{\circ}C$ 

Figure 70

50

100

125

75

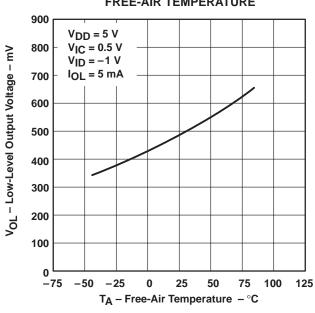
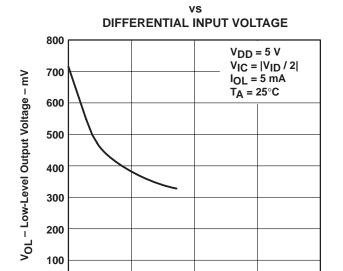


Figure 72



LOW-LEVEL OUTPUT VOLTAGE
vs
LOW-LEVEL OUTPUT CURRENT

-4

V<sub>ID</sub> - Differential Input Voltage - V

Figure 71

-6

-8

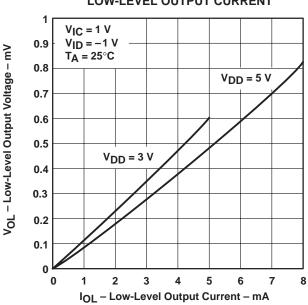
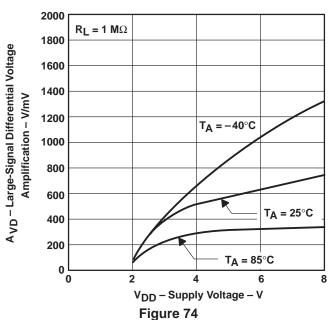
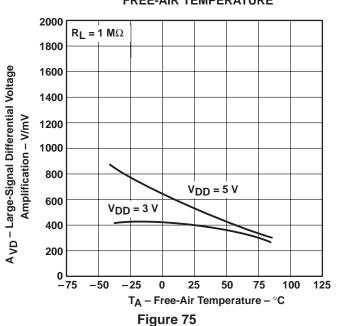


Figure 73

# LARGE-SIGNAL DIFFERENTIAL VOLTAGE AMPLIFICATION vs SUPPLY VOLTAGE

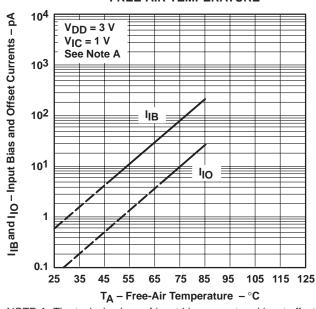


# LARGE-SIGNAL DIFFERENTIAL VOLTAGE AMPLIFICATION vs FREE-AIR TEMPERATURE



# INPUT BIAS CURRENT AND INPUT OFFSET CURRENT

### FREE-AIR TEMPERATURE



NOTE A: The typical values of input bias current and input offset current below 5 pA are determined mathematically.

Figure 76

COMMON-MODE INPUT VOLTAGE POSITIVE LIMIT

### SUPPLY VOLTAGE

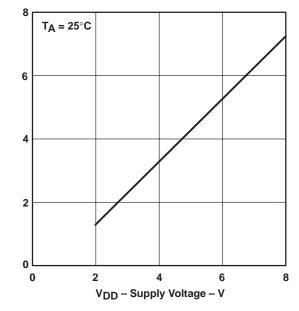
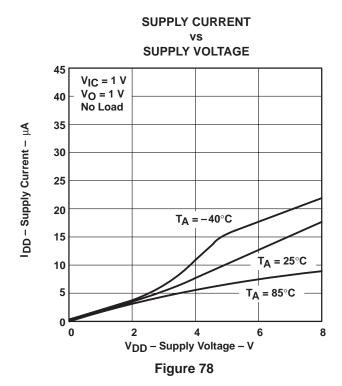


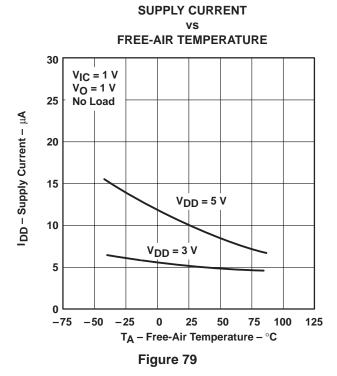
Figure 77

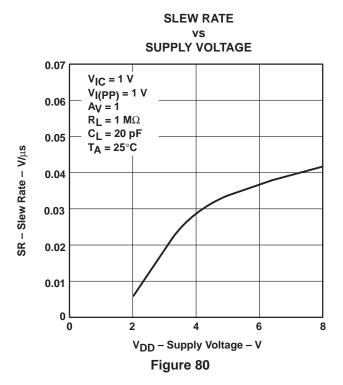
- Common-Mode Input Voltage

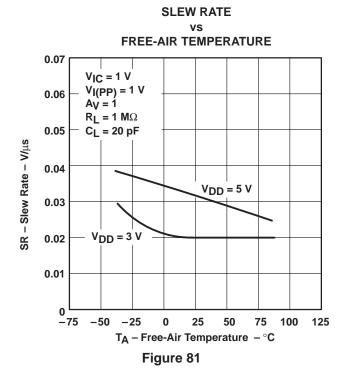
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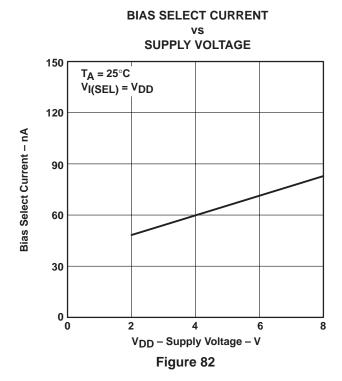


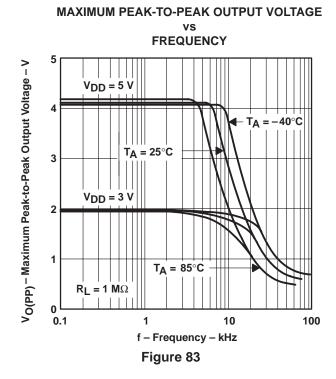


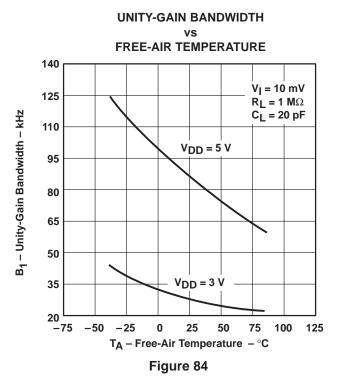


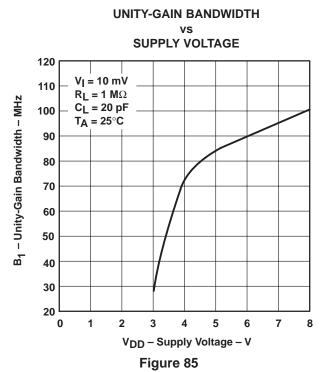












## LARGE-SIGNAL DIFFERENTIAL VOLTAGE AMPLIFICATION AND PHASE SHIFT

### vs **FREQUENCY** 107 A<sub>VD</sub> - Large-Signal Differential Voltage Amplification -60° $V_{DD} = 3 V$ C<sub>L</sub> = 20 pF 106 $R_L = 1 M\Omega$ $T_A = 25^{\circ}C$ -30° 10<sup>5</sup> **0**° 104 **30**° Phase Shift AVD 103 60° 102 90° **Phase Shift** 101 120° 150° 1 180° 0.1 10 100 1 k 10 k 100 k 1 M

Figure 86

# LARGE-SIGNAL DIFFERENTIAL VOLTAGE AMPLIFICATION AND PHASE SHIFT

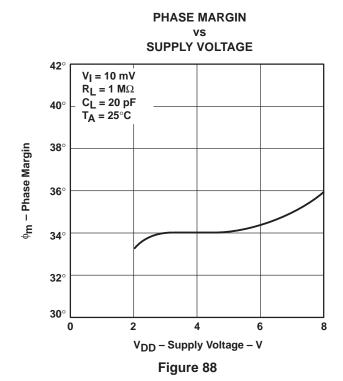
f - Frequency - Hz

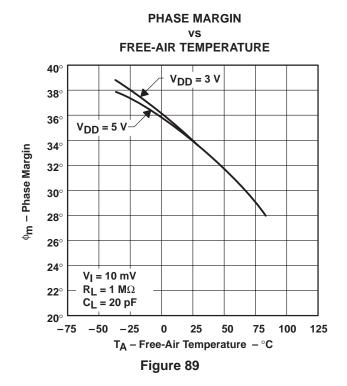
**FREQUENCY** 107 -60° A<sub>VD</sub> – Large-Signal Differential Voltage Amplification  $V_{DD} = 5 V$  $C_L = 20 pF$ 10<sup>6</sup> -30°  $R_L = 1 M\Omega$  $T_A = 25^{\circ}C$ 105 **0**° 104 Phase Shift **30**° AVD 103 60° 102 90° **Phase Shift** 10<sup>1</sup> 120° 150° 1 0.1 180° 10 100 1 k 10 k 100 k 1 M 1 f - Frequency - Hz

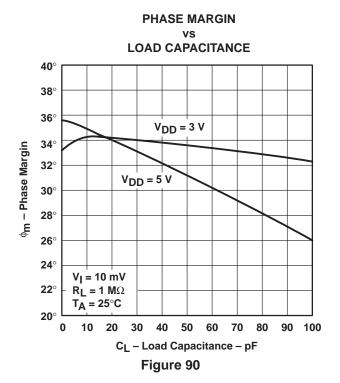
Figure 87

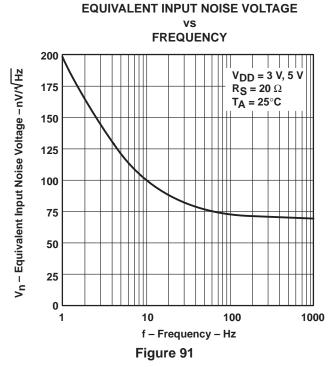


### TYPICAL CHARACTERISTICS (LOW-BIAS MODE)









### PARAMETER MEASUREMENT INFORMATION

### single-supply versus split-supply test circuits

Because the TLV2341 is optimized for single-supply operation, circuit configurations used for the various tests often present some inconvenience since the input signal, in many cases, must be offset from ground. This inconvenience can be avoided by testing the device with split supplies and the output load tied to the negative rail. A comparison of single-supply versus split-supply test circuits is shown below. The use of either circuit gives the same result.

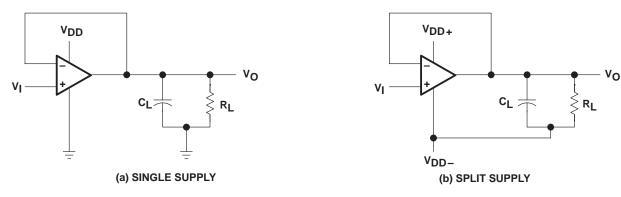


Figure 92. Unity-Gain Amplifier

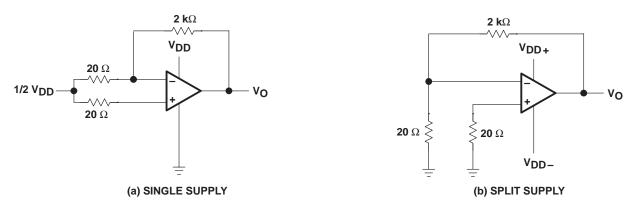


Figure 93. Noise-Test Circuits

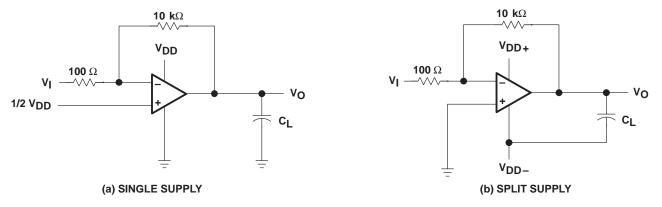


Figure 94. Gain-of-100 Inverting Amplifier



### PARAMETER MEASUREMENT INFORMATION

### input bias current

Because of the high input impedance of the TLV2341 operational amplifier, attempts to measure the input bias current can result in erroneous readings. The bias current at normal ambient temperature is typically less than 1 pA, a value that is easily exceeded by leakages on the test socket. Two suggestions are offered to avoid erroneous measurements:

- Isolate the device from other potential leakage sources. Use a grounded shield around and between the device inputs (see Figure 95). Leakages that would otherwise flow to the inputs are shunted away.
- Compensate for the leakage of the test socket by actually performing an input bias current test (using a
  picoammeter) with no device in the test socket. The actual input bias current can then be calculated by
  subtracting the open-socket leakage readings from the readings obtained with a device in the test
  socket.

Many automatic testers as well as some bench-top operational amplifier testers use the servo-loop technique with a resistor in series with the device input to measure the input bias current (the voltage drop across the series resistor is measured and the bias current is calculated). This method requires that a device be inserted into the test socket to obtain a correct reading; therefore, an open-socket reading is not feasible using this method.

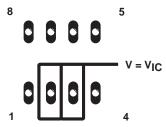


Figure 95. Isolation Metal Around Device Inputs (P package)

### low-level output voltage

To obtain low-level supply-voltage operation, some compromise is necessary in the input stage. This compromise results in the device low-level output voltage being dependent on both the common-mode input voltage level as well as the differential input voltage level. When attempting to correlate low-level output readings with those quoted in the electrical specifications, these two conditions should be observed. If conditions other than these are to be used, please refer to the Typical Characteristics section of this data sheet.

### input offset voltage temperature coefficient

Erroneous readings often result from attempts to measure temperature coefficient of input offset voltage. This parameter is actually a calculation using input offset voltage measurements obtained at two different temperatures. When one (or both) of the temperatures is below freezing, moisture can collect on both the device and the test socket. This moisture results in leakage and contact resistance which can cause erroneous input offset voltage readings. The isolation techniques previously mentioned have no effect on the leakage since the moisture also covers the isolation metal itself, thereby rendering it useless. These measurements should be performed at temperatures above freezing to minimize error.

### full-power response

Full-power response, the frequency above which the operational amplifier slew rate limits the output voltage swing, is often specified two ways: full-linear response and full-peak response. The full-linear response is



### PARAMETER MEASUREMENT INFORMATION

generally measured by monitoring the distortion level of the output while increasing the frequency of a sinusoidal input signal until the maximum frequency is found above which the output contains significant distortion. The full-peak response is defined as the maximum output frequency, without regard to distortion, above which full peak-to-peak output swing cannot be maintained.

Because there is no industry-wide accepted value for significant distortion, the full-peak response is specified in this data sheet and is measured using the circuit of Figure 92. The initial setup involves the use of a sinusoidal input to determine the maximum peak-to-peak output of the device (the amplitude of the sinusoidal wave is increased until clipping occurs). The sinusoidal wave is then replaced with a square wave of the same amplitude. The frequency is then increased until the maximum peak-to-peak output can no longer be maintained (Figure 96). A square wave is used to allow a more accurate determination of the point at which the maximum peak-to-peak output is reached.

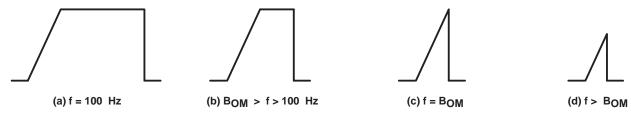


Figure 96. Full-Power-Response Output Signal

### test time

Inadequate test time is a frequent problem, especially when testing CMOS devices in a high-volume, short-test-time environment. Internal capacitances are inherently higher in CMOS than in bipolar and BiFET devices and require longer test times than their bipolar and BiFET counterparts. The problem becomes more pronounced with reduced supply levels and lower temperatures.

### **APPLICATION INFORMATION**

### single-supply operation

While the TLV2341 performs well using dual-power supplies (also called balanced or split supplies), the design is optimized for single-supply operation. This includes an input common-mode voltage range that encompasses ground as well as an output voltage range that pulls down to ground. The supply voltage range extends down to 2 V, thus allowing operation with supply levels commonly available for TTL and HCMOS.

Many single-supply applications require that a voltage be applied to one input to establish a reference level that is above ground. This virtual ground can be generated using two large resistors, but a preferred technique is to use a virtual-ground generator such as the TLE2426. The TLE2426 supplies an accurate voltage equal to  $V_{DD}/2$ , while consuming very little power and is suitable for supply voltages of greater than 4 V.

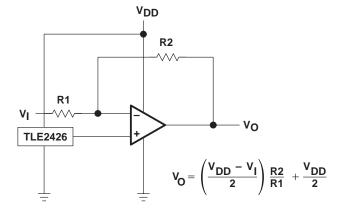


Figure 97. Inverting Amplifier With Voltage Reference

### **APPLICATION INFORMATION**

### single-supply operation (continued)

The TLV2341 works well in conjunction with digital logic; however, when powering both linear devices and digital logic from the same power supply, the following precautions are recommended:

- Power the linear devices from separate bypassed supply lines (see Figure 98); otherwise, the linear device supply rails can fluctuate due to voltage drops caused by high switching currents in the digital logic.
- Use proper bypass techniques to reduce the probability of noise-induced errors. Single capacitive decoupling is often adequate; however, RC decoupling may be necessary in high-frequency applications.

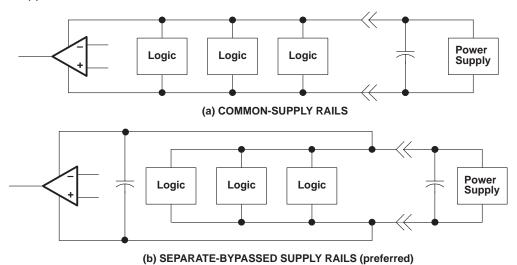


Figure 98. Common Versus Separate Supply Rails

### input offset voltage nulling

The TLV2341 offers external input offset null control. Nulling of the input offset voltage can be achieved by adjusting a 25-k $\Omega$  potentiometer connected between the offset null terminals with the wiper connected as shown in Figure 99. The amount of nulling range varies with the bias selection. In the high-bias mode, the nulling range allows the maximum offset voltage specified to be trimmed to zero. In low-bias and medium-bias modes, total nulling may not be possible.



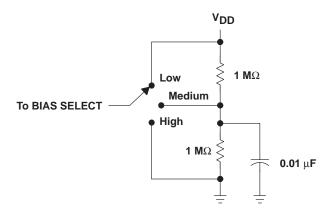
Figure 99. Input Offset Voltage Null Circuit



### APPLICATION INFORMATION

### bias selection

Bias selection is achieved by connecting the bias-select pin to one of the three voltage levels (see Figure 100). For medium-bias applications, it is recommended that the bias-select pin be connected to the midpoint between the supply rails. This is a simple procedure in split-supply applications, since this point is ground. In single-supply applications, the medium-bias mode necessitates using a voltage divider as indicated. The use of large-value resistors in the voltage divider reduces the current drain of the divider from the supply line. However, large-value resistors used in conjunction with a large-value capacitor require significant time to charge up to the supply midpoint after the supply is switched on. A voltage other than the midpoint may be used if it is within the voltages specified in the following table.



BIAS MODE	BIAS-SELECT VOLTAGE (single supply)
Low	$V_{DD}$
Medium	1 V to V <sub>DD</sub> –1 V
High	GND

Figure 100. Bias Selection for Single-Supply Applications

### input characteristics

The TLV2341 is specified with a minimum and a maximum input voltage that, if exceeded at either input, could cause the device to malfunction. Exceeding this specified range is a common problem, especially in single-supply operation. The lower the range limit includes the negative rail, while the upper range limit is specified at  $V_{DD} - 1$  V at  $T_A = 25$ °C and at  $V_{DD} - 1.2$  V at all other temperatures.

The use of the polysilicon-gate process and the careful input circuit design gives the TLV2341 good input offset voltage drift characteristics relative to conventional metal-gate processes. Offset voltage drift in CMOS devices is highly influenced by threshold voltage shifts caused by polarization of the phosphorus dopant implanted in the oxide. Placing the phosphorus dopant in a conductor (such as a polysilicon gate) alleviates the polarization problem, thus reducing threshold voltage shifts by more than an order of magnitude. The offset voltage drift with time has been calculated to be typically  $0.1~\mu V/month$ , including the first month of operation.

Because of the extremely high input impedance and resulting low bias-current requirements, the TLV2341 is well suited for low-level signal processing; however, leakage currents on printed-circuit boards and sockets can easily exceed bias-current requirements and cause a degradation in device performance. It is good practice to include guard rings around inputs (similar to those of Figure 95 in the Parameter Measurement Information section). These guards should be driven from a low-impedance source at the same voltage level as the common-mode input (see Figure 101).

The inputs of any unused amplifiers should be tied to ground to avoid possible oscillation.



### **APPLICATION INFORMATION**

### input characteristics (continued)

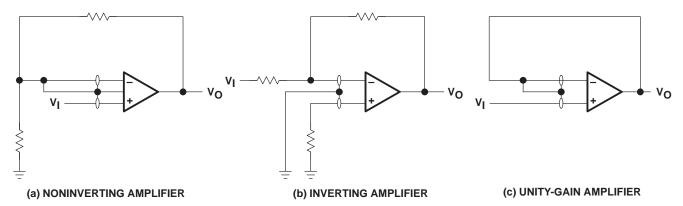


Figure 101. Guard-Ring Schemes

### noise performance

The noise specifications in operational amplifiers circuits are greatly dependent on the current in the first-stage differential amplifier. The low input bias-current requirements of the TLV2341 results in a very low noise current, which is insignificant in most applications. This feature makes the device especially favorable over bipolar devices when using values of circuit impedance greater than 50 k $\Omega$ , since bipolar devices exhibit greater noise currents.

### feedback

Operational amplifier circuits nearly always employ feedback, and since feedback is the first prerequisite for oscillation, caution is appropriate. Most oscillation problems result from driving capacitive loads and ignoring stray input capacitance. A small-value capacitor connected in parallel with the feedback resistor is an effective remedy (see Figure 102). The value of this capacitor is optimized empirically.

Figure 102. Compensation for Input Capacitance

### electrostatic-discharge protection

The TLV2341 incorporates an internal electrostatic-discharge (ESD)-protection circuit that

prevents functional failures at voltages up to 2000 V as tested under MIL-STD-883C, Method 3015.2. Care should be exercised, however, when handling these devices as exposure to ESD may result in the degradation of the device parametric performance. The protection circuit also causes the input bias currents to be temperature dependent and have the characteristics of a reverse-biased diode.

### latch-up

Because CMOS devices are susceptible to latch-up due to their inherent parasitic thyristors, the TLV2341 inputs and output are designed to withstand – 100-mA surge currents without sustaining latch-up; however, techniques should be used to reduce the chance of latch-up whenever possible. Internal protection diodes should not by



### APPLICATION INFORMATION

design be forward biased. Applied input and output voltage should not exceed the supply voltage by more that 300 mV. Care should be exercised when using capacitive coupling on pulse generators. Supply transients should be shunted by the use of decoupling capacitors (0.1  $\mu$ F typical) located across the supply rails as close to the device as possible.

The current path established if latch-up occurs is usually between the positive supply rail and ground and can be triggered by surges on the supply lines and/or voltages on either the output or inputs that exceed the supply voltage. Once latch-up occurs, the current flow is limited only by the impedance of the power supply and the forward resistance of the parasitic thyristor and usually results in the destruction of the device. The chance of latch-up occurring increases with increasing temperature and supply voltages.

### output characteristics

The output stage of the TLV2341 is designed to sink and source relatively high amounts of current (see Typical Characteristics). If the output is subjected to a short-circuit condition, this high-current capability can cause device damage under certain conditions. Output current capability increases with supply voltage.

Although the TLV2341 possesses excellent high-level output voltage and current capability, methods are available for boosting this capability if needed. The simplest method involves the use of a pullup resistor (Rp) connected from the output to the positive supply rail (see Figure 103). There are two disadvantages to the use of this circuit. First, the NMOS pulldown transistor N4 (see equivalent schematic) must sink a comparatively large amount of current. In this circuit, N4 behaves like a linear resistor with an on resistance between approximately  $60 \Omega$  and  $180 \Omega$ , depending on how hard the operational amplifier input is driven. With very low values of Rp, a voltage offset from 0 V at the output occurs. Secondly, pullup resistor R<sub>P</sub> acts as a drain load to N4 and the gain of the operational amplifier is reduced at output voltage levels where N5 is not supplying the output current.

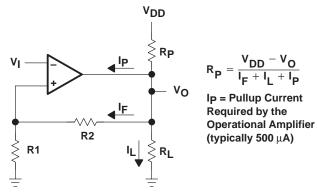


Figure 103. Resistive Pullup to Increase VOH

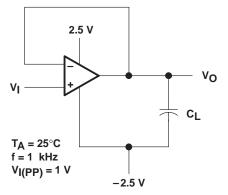


Figure 104. Test Circuit for Output Characteristics

All operating characteristics of the TLV2341 are measured using a 20-pF load. The device drives higher capacitive loads; however, as output load capacitance increases, the resulting response pole occurs at lower frequencies thereby causing ringing, peaking, or even oscillation (see Figures 105, 106 and 107). In many cases, adding some compensation in the form of a series resistor in the feedback loop alleviates the problem.

### **APPLICATION INFORMATION**

### output characteristics (continued)

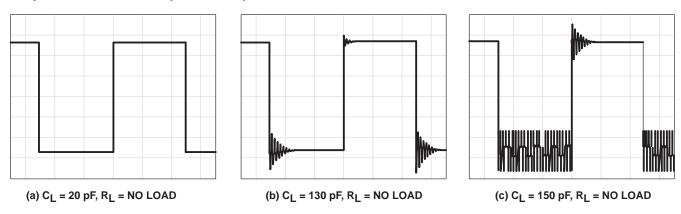


Figure 105. Effect of Capacitive Loads in High-Bias Mode

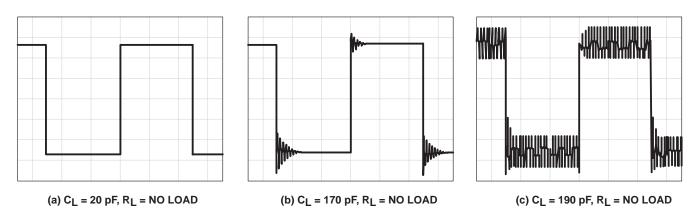


Figure 106. Effect of Capacitive Loads in Medium-Bias Mode

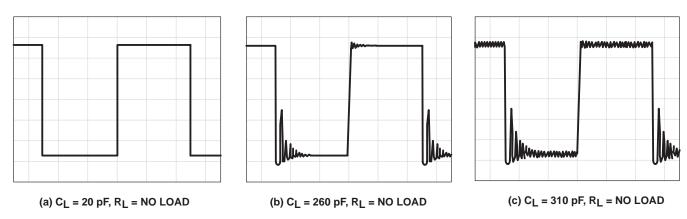


Figure 107. Effect of Capacitive Loads in Low-Bias Mode







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### **PACKAGING INFORMATION**

Orderable Device	Status <sup>(1)</sup>	Package Type	Package Drawing	Pins	Package Qty	Eco Plan <sup>(2)</sup>	Lead/ Ball Finish	MSL Peak Temp <sup>(3)</sup>	Samples (Requires Login)
TLV2341ID	ACTIVE	SOIC	D	8	75	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
TLV2341IDG4	ACTIVE	SOIC	D	8	75	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
TLV2341IDR	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
TLV2341IDRG4	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
TLV2341IP	ACTIVE	PDIP	Р	8		TBD	Call TI	Call TI	
TLV2341IPE4	ACTIVE	PDIP	Р	8		TBD	Call TI	Call TI	
TLV2341IPWLE	OBSOLETE	TSSOP	PW	8		TBD	Call TI	Call TI	

<sup>(1)</sup> The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

**OBSOLETE:** TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check http://www.ti.com/productcontent for the latest availability information and additional product content details.

**TBD:** The Pb-Free/Green conversion plan has not been defined.

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the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

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(3) MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

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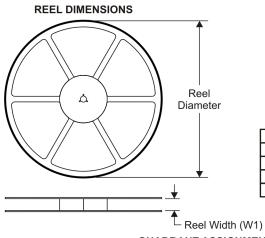
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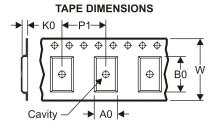
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### PACKAGE MATERIALS INFORMATION

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### TAPE AND REEL INFORMATION





A0	Dimension designed to accommodate the component width
B0	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



### \*All dimensions are nominal

Device	Package Type	Package Drawing			Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
TLV2341IDR	SOIC	D	8	2500	330.0	12.4	6.4	5.2	2.1	8.0	12.0	Q1

www.ti.com 23-Sep-2010



### \*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
TLV2341IDR	SOIC	D	8	2500	340.5	338.1	20.6

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